

# NOT RECOMMENDED FOR NEW DESIGN USE DMN3025SFV



DMG7408SFG

### 30V N-CHANNEL ENHANCEMENT MODE MOSFET PowerDI3333-8

# **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D</sub> Max T <sub>A</sub> = +25°C
	23mΩ @ V <sub>GS</sub> = 10V	7.0A
30V	$33\text{m}\Omega$ @ $V_{GS} = 4.5V$	6.0A

### **Features and Benefits**

- 100% Unclamped Inductive Switch (UIS) Test in Production
- Low R<sub>DS(ON)</sub> Ensures On State Losses Are Minimized
- Small Form Factor Thermally Efficient Package Enables Higher Density End Products
- Occupies Just 33% of The Board Area Occupied by SO-8 Enabling Smaller End Product
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

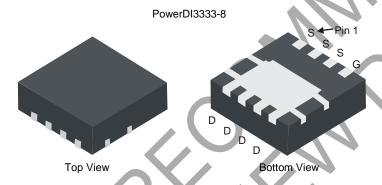
## **Description and Applications**

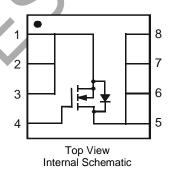
This MOSFET has been designed to minimize the on-state resistance  $(R_{DS(ON)})$  and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Backlighting
- Power Management Functions
- DC-DC Converters

### **Mechanical Data**

- Case: PowerDI<sup>®</sup>3333-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
  Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.008 grams (Approximate)





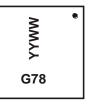
### Ordering Information (Note 4)

Part Number	Case	Packaging
DMG7408SFG-7	PowerDI3333-8	2000/Tape & Reel
DMG7408SFG-13	PowerDI3333-8	3000/Tape & Reel

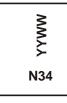
Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

# **Marking Information**



G78 = Product Type Marking Code YYWW = Date Code Marking YY = Last Two Digits of Year (ex: 17 = 2017) WW = Week Code (01 to 53)



N34 = Product Type Marking Code YYWW = Date Code Marking YY = Last Two Digits of Year (ex: 17 = 2017) WW = Week Code (01 to 53)

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# **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	$V_{DSS}$	30	V		
Gate-Source Voltage	$V_{GSS}$	±20	V		
Continuous Drain Current (Note 5) \/ 10\/	Steady State	$T_A = +25$ °C $T_A = +70$ °C	Ι <sub>D</sub>	7.0 5.5	А
Continuous Drain Current (Note 5) V <sub>GS</sub> = 10V	t<10s	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I <sub>D</sub>	9.5 7.5	А
Continuous Drain Current (Note 5) V <sub>GS</sub> = 4.5V	Steady State	$T_A = +25$ °C $T_A = +70$ °C	I <sub>D</sub>	6.0 5.7	А
Continuous Diam Current (Note 5) VGS = 4.5V	t<10s	$T_A = +25$ °C $T_A = +70$ °C	Ι <sub>D</sub>	8.0 6.3	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I <sub>DM</sub>	66	Α		
Maximum Continuous Body Diode Forward Current (I	Is	3.0	Α		
Avalanche Current (Note 7)	I <sub>AS</sub>	9	Α		
Avalanche Energy (Note 7)	E <sub>AS</sub>	12	mJ		

# Thermal Characteristics ( $@T_A = +25^{\circ}C$ , unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 6)		P <sub>D</sub>	1	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	Р.,	131	°C/W
Thermal Resistance, Junction to Ambient (Note 6)	t<10s	$R_{\theta}$ JA	72	°C/W
Total Power Dissipation (Note 5)		P <sub>D</sub>	2.1	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State		63	°C/W
Thermal Nesistance, Junction to Ambient (Note 3)	t<10s	$R_{\theta JA}$	35	°C/W
Thermal Resistance, Junction to Case (Note 5)		$R_{ heta JC}$	7.1	°C/W
Operating and Storage Temperature Range		$T_{J_r}T_{STG}$	-55 to +150	°C

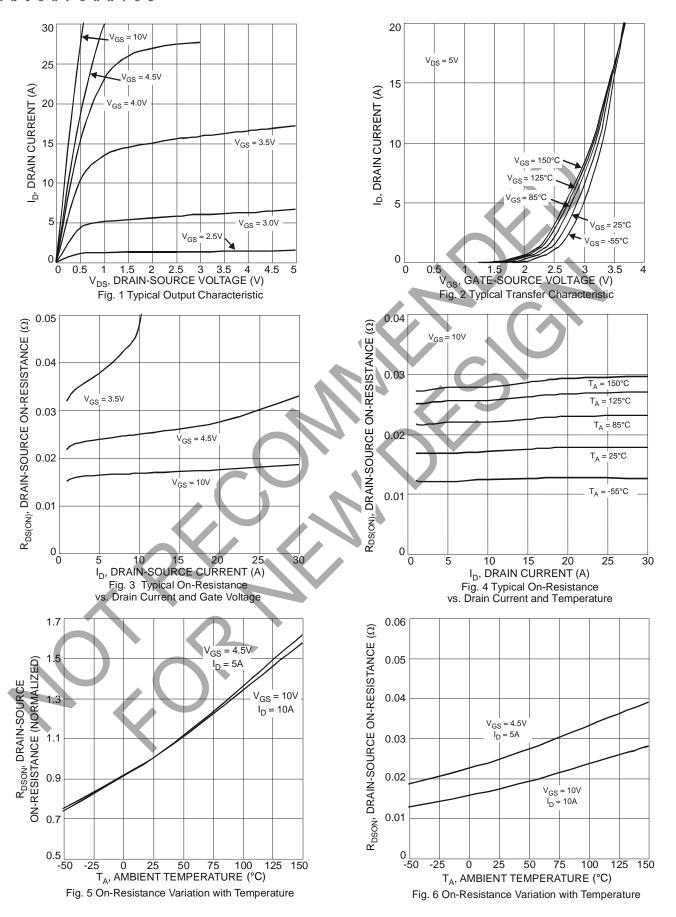
# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	30	-	-	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>		-	1	μΑ	$V_{DS} = 30V, V_{GS} = 0V$	
Gate-Source Leakage	Igss	-	-	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	$V_{GS(TH)}$	1.0	1.45	2.4	٧	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
Static Drain-Source On-Resistance			15	23 33	mΩ	$V_{GS} = 10V, I_D = 10A$	
Static Dialif-Source Off-Resistance	R <sub>DS(ON)</sub>	-	25			$V_{GS} = 4.5V, I_D = 7.5A$	
Forward Transfer Admittance	Y <sub>fs</sub>	-	11	-	S	$V_{DS} = 5V, I_{D} = 10A$	
Diode Forward Voltage	$V_{SD}$	-	0.72	1	V	$V_{GS} = 0V, I_{S} = 1A$	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	Ciss	-	478.9	-	pF	), 45V, V, 0V,	
Output Capacitance	Coss	-	96.7	1	pF	$V_{DS} = 15V, V_{GS} = 0V,$ f = 1.0MHz	
Reverse Transfer Capacitance	C <sub>rss</sub>	-	61.4	-	pF	1 = 1.000112	
Gate Resistance	$R_g$	0.4	1.1	1.6	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge (V <sub>GS</sub> = 4.5V)	Qg	-	5.0	8			
Total Gate Charge (V <sub>GS</sub> = 10V)	$Q_g$	-	10.5	17	nC   45VI 40A		
Gate-Source Charge	Q <sub>gs</sub>	-	1.8	-	nC	$V_{DS} = 15V, I_D = 10A$	
Gate-Drain Charge	$Q_{gd}$	-	1.6	-	nC		
Turn-On Delay Time	t <sub>D(ON)</sub>	-	2.9	-	ns	V <sub>GS</sub> = 10V, V <sub>DS</sub> = 15V,	
Turn-On Rise Time	t <sub>R</sub>	-	7.9	-	ns		
Turn-Off Delay Time	t <sub>D(OFF)</sub>	-	14.6	-	ns	$R_G = 3\Omega$ , $R_L = 1.5\Omega$	
Turn-Off Fall Time	t <sub>F</sub>	-	3.1	-	ns		

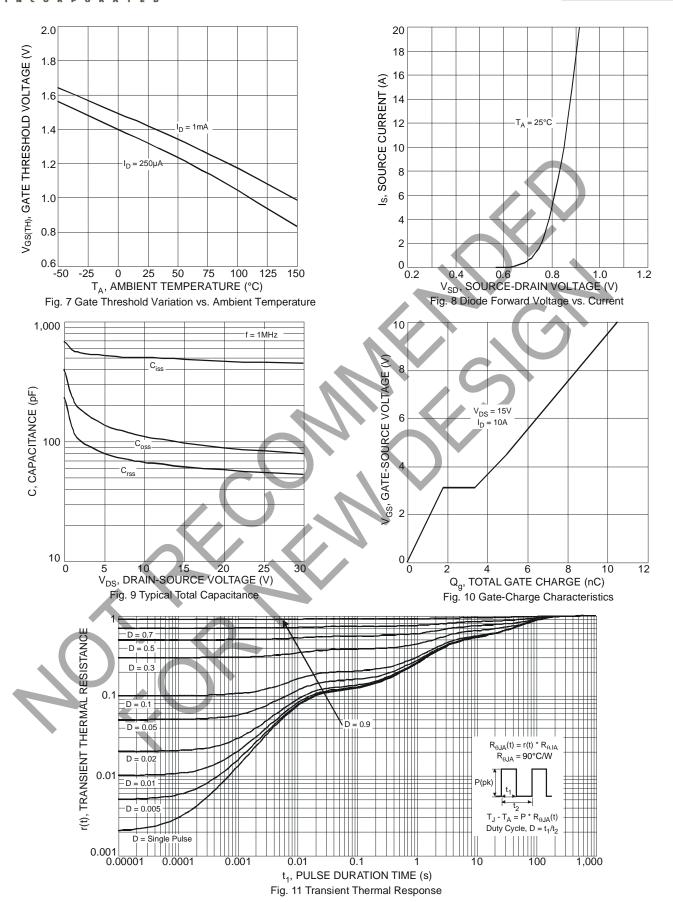
Notes:

- $5. R_{\text{OJA}}$  is determined with the device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
- 7. UIS in production with L = 0.3 mH,  $T_J = +25 ^{\circ}\text{C}$ .
- S. Short duration pulse test used to minimize self-heating effect.
  Guaranteed by design. Not subject to product testing.







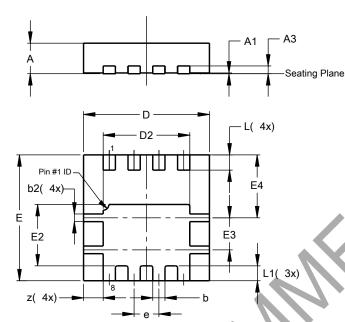




# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### PowerDI3333-8

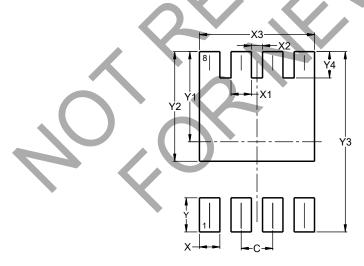


PowerDI3333-8						
Dim	Min	Max	Тур			
Α	0.75	0.85	0.80			
A1	0.00	0.05	0.02			
A3	-	-	0.203			
b	0.27	0.37	0.32			
b2	0.15	0.25	0.20			
D	3.25	3.35	3.30			
D2	2.22	2.32	2.27			
E	3.25	3.35	3.30			
E2	1.56	1.66	1.61			
E3	0.79	0.89	0.84			
E4	1.60	1.70	1.65			
е	_	_	0.65			
L	0.35	0.45	0.40			
L1	_	-	0.39			
Z	_	_	0.515			
All Dimensions in mm						

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### PowerDI3333-8



Dimensions	Value (in mm)
С	0.650
Х	0.420
X1	0.420
X2	0.230
Х3	2.370
Y	0.700
Y1	1.850
Y2	2.250
Y3	3.700
V۸	0.540



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